

Quad Digital Switch

Advanced Information

Features

- 4,096 × 4,096 channel non-blocking switching at 8.192 or 16.384 Mb/s
- Per-channel variable or constant throughput delay
- Accept ST-BUS streams of 2.048Mb/s, 4.096Mb/s, 8.192Mb/s, or 16.384 Mb/s
- Split Rate mode allows mix of two bit rates and rate conversions
- Automatic frame offset delay measurement for ST-BUS input and output streams
- Per-stream frame delay offset programming
- Per-channel high impedance output control
- Bit Error Monitoring on selected ST-BUS input and output channels.
- · Per-channel message mode
- · Connection memory block programming
- IEEE-1149.1 (JTAG) Test Port
- 3.3V local I/O with 5V tolerant inputs and TTL compatible outputs

Applications

- Medium and large switching platforms
- CTI application
- Voice/data multiplexer
- · Digital cross connects
- WAN access system
- · Wireless base stations

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Ordering Information

MT90826AL 160 Pin MQFP MT90826AG 160 Pin PBGA

-40 to +85 C

Description

The MT90826 Quad Digital Switch has a non-blocking switch capacity of 4,096 x 4,096 channels at a serial bit rate of 8.192Mb/s or 16.384 Mb/s, 2,048 x 2,048 channels at 4.096Mb/s and 1024 x 1024 channels at 2.048Mb/s. The device has many features that are programmable on a per stream or per channel basis, including message mode, input offset delay and high impedance output control.

The per stream input and output delay control is particularly useful for managing large multi-chip switches with a distributed backplane.

Operating in Split Rate mode allows for switching between two groups of bit rate streams.

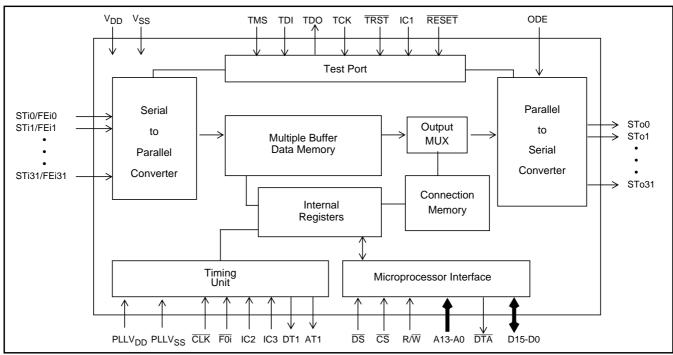


Figure 1 - Functional Block Diagram

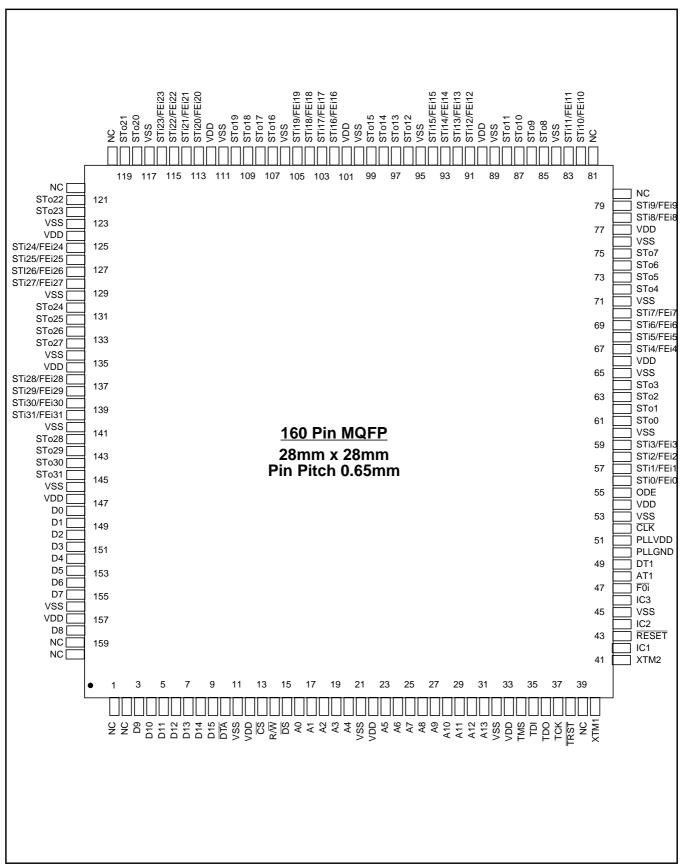


Figure 2 - 160-Pin MQFP Pin Connections

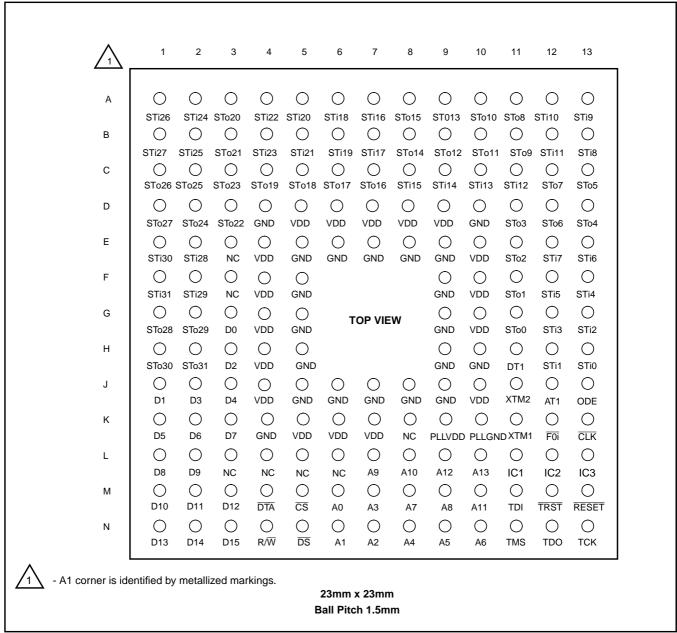


Figure 3 - 160-Pin PBGA Pin Connections

Pin Description

Pin # MQFP	Pin # PBGA	Name	Description
12,22,33,54, 66,77,90,101, 112,125,136, 147,157	D5,D6,D7,D8,D9, E4,E10,F4, F10,G4,G10, H4,J4,J10,K5, K6,K7	V _{DD}	+3.3 Volt Power Supply
11,21,32,45, 53,60,65,71, 76,84,89,95, 100,106,111, 117,124,130, 135,141,146, 156	D4,D10,E5,E6,E7 , E8,E9,F5,F9,G5, G9,H5,H9,H10,J5 , J6,J7,J8,J9,K4	V _{ss}	Ground

Pin Description (continued)

Pin # MQFP	Pin # PBGA	Name	Description
34	N11	TMS	Test Mode Select (3.3V Input with Internal pull-up): JTAG signal that controls the state transitions of the TAP controller. This pin is pulled high by an internal pull-up when not driven.
35	M11	TDI	Test Serial Data In (3.3V Input with Internal pull-up): JTAG serial test instructions and data are shifted in on this pin. This pin is pulled high by an internal pull-up when not driven.
36	N12	TDO	Test Serial Data Out (3.3V Output): JTAG serial data is output on this pin on the falling edge of TCK. This pin is held in high impedance state when JTAG scan is not enabled.
37	N13	тск	Test Clock (5V Tolerant Input): Provides the clock to the JTAG test logic.
38	M12	TRST	Test Reset (3.3V Input with internal pull-up): Asynchronously initializes the JTAG TAP controller by putting it in the Test-Logic-Reset state. This pin is pulled by an internal pull-up when not driven. This pin should be pulsed low on power-up, or held low, to ensure that the device is in the normal functional mode.
40	K11	XTM1	PLL Test Access 1 (3.3V Input): Use for PLL testing only. No connect for normal operation.
41	J11	XTM2	PLL Test Access 1 (3.3V Input): Use for PLL testing only. No connect for normal operation.
42	L11	IC1	Internal Connection 1 (3.3V Input with internal pull-down): Connect to V _{SS} for normal operation.
43	M13	RESET	Device Reset (5V Tolerant Input): This input (active LOW) puts the device in its reset state which clears the device internal counters and registers.
44	L12	IC2	Internal Connection 2 (3.3V Input with internal pull-down): Connect to V _{SS} for normal operation. When IC3 pin is tied to 3.3V, this pin is used as the PLL bypass clock input for PLL testing only.
46	L13	IC3	Internal Connection 3 (3.3V Input with internal pull-down): Connect to V _{SS} for normal operation. When this pin is tied to 3.3V, it enables the PLL bypass mode for PLL testing only.
47	K12	F 0i	Master Frame Pulse (5V Tolerant Input): This input accepts a 60ns wide negative frame pulse.
48	J12	AT1	Analog Test Access (Bidirectional): Use for PLL testing only. No connect for normal operation.
49	H11	DT1	Digital Test Access Output (Output): Use for PLL testing only. No connect for normal operation.
50	K10	PLLGND	Phase Lock Loop Ground.
51	K9	PLLVDD	Phase Lock Loop Power Supply: 3.3V

Pin Description (continued)

Pin # MQFP	Pin # PBGA	Name	Description
52	K13	CLK	Master Clock (5V Tolerant Input): Serial clock for shifting data in/out on the serial streams. This pin accepts a clock frequency of 8.192MHz or 16.384 MHz. The CPLL bit in the control register determines the usage of the clock frequency. See Table 6 for details.
55	J13	ODE	Output Drive Enable (5V Tolerant Input): This is the output-enable control pin for the STo0 to STo31 serial outputs. See Table 2 for details.
56 57 58 59 67-70 78,79 82,83 91-94 102-105 113-116 126-129 137-140	H13 H12 G13 G12 F13,F12,E13,E12 B13,A13 A12,B12 C11,C10,C9,C8 A7,B7,A6,B6 A5,B5,A4,B4 A2,B2,A1,B1 E2,F2,E1,F1	STi0/FEi0, STi1/FEi1 STi2/FEi2 STi3/FEi3 STi4-7/FEi4-7 STi8-9/FEi8-9 STi10-11/FEi10-11 STi12-15/FEi12-15 STi16-19/FEi16-19 STi20-23/FEi20-23 STi24-27/FEi24-27 STi28-31/FEi28-31	Serial Input Streams 0 to 31 and Frame Evaluation Inputs 0 to 31 (5V Tolerant Inputs): Serial data input streams. These streams may have data rates of 2.048, 4.096, 8.192 or 16.384 Mb/s, depending upon the value programmed at bits DR0 - DR2 in the control register. In the frame evaluation mode, they are used as the frame evaluation inputs.
61-64 72-75 85-88 96-99 107-110 118,119 122,123 131-134 142-145	G11,F11,E11,D11 D13,C13,D12,C12 A11,B11,A10,B10 B9,A9,B8,A8 C7,C6,C5,C4 A3,B3 D3,C3 D2,C2,C1,D1 G1,G2,H1,H2	ST00 - 3 ST04 - 7 ST08 - 11 ST012 - 15 ST016 - 19 ST020, ST021 ST022, ST023 ST024 - 27 ST028 - 31	ST-BUS Output 0 to 31 (Three-state Outputs). Serial data output streams. These streams may have data rates of 2.048, 4.096, 8.192, or 16.384 Mb/s, depending upon the value programmed at bits DR0 - DR2 in the control register.
148-153 154,155 158 3-7 8,9	G3,J1,H3,J2,J3,K1, K2,K3 L1 L2,M1,M2,M3,N1, N2,N3	D0 - 5, D6,D7 D8 D9 - 13 D14,D15	Data Bus 0 -15 (5V Tolerant I/O): These pins form the 16-bit data bus of the microprocessor port.
10	M4	DTA	Data Transfer Acknowledgment (Three-state Output): This output pulses low from tristate to indicate that a databus transfer is complete. A pull-up resistor is required to hold a HIGH level when the pin is tristated.
15	N5	DS	Data Strobe (5V Tolerant Input): This active low input works in conjunction with \overline{CS} to enable the read and write operations.
14	N4	R/W	Read/Write (5V Tolerant Input): This input controls the direction of the data bus lines (D0-D15) during a microprocessor access.
13	M5	CS	Chip Select (5V Tolerant Input): Active low input used by a microprocessor to activate the microprocessor port.
16-20 23-31	M6,N6,N7,M7,N8 N9,N10,M8,M9,L7 L8,M10,L9,A10	A0 - A4 A5-A13	Address 0 - 13 (5V Tolerant Input): These lines provide the A0 - A13 address lines when accessing the internal registers or memories.
1,2,39,80,81,120, 121,159,160	E3,F3,K8, L3,L4,L5,L6	NC	No Connect

Device Overview

The MT90826 Quad Digital Switch is capable of switching up to $4{,}096 \times 4{,}096$ channels. The MT90826 is designed to switch 64 kbit/s PCM or N x 64k bit/s data. The device maintains frame integrity in data applications and minimum throughput delay for voice applications on a per channel basis.

The serial input streams of the MT90826 can have a bit rate of 2.048, 4.096, 8.192 or 16.384 Mbit/s and are arranged in 125 μ s wide frames, which contain 32, 64,128 or 256 channels, respectively. The data rates on input and output streams match. All inputs and outputs may be programmed to 2.048, 4.096 or 8.192 Mb/s. STi0-15 and STo0-15 may be set to 16.384 Mb/s. Combinations of two bit rates, *N* and *2N* are provided. See Table 1.

By using Mitel's message mode capability, the microprocessor can access input and output timeslots on a per channel basis. This feature is useful for transferring control and status information for external circuits or other ST-BUS devices.

The frame offset calibration function allows users to measure the frame offset delay for streams STi0 to STi31. The offset calibration is activated by a frame evaluation bit in the frame evaluation register. The evaluation result is stored in the frame evaluation registers and can be used to program the input offset delay for individual streams using internal frame input offset registers.

The microport interface is compatible with Motorola non-multiplexed buses. Connection memory locations may be directly written to or read from; data memory locations may be directly read from. A DTA signal is provided to hold the bus until the asynchronous microport operation is queued into the device. For applications that require no wait states, indirect reading and writing may be used. Intermediary registers are directly programmed with the write data and address, or read address. The data in the intermediary registers is internally transferred synchronous with the operation of the internal state machines. Completion of the operation is indicated by a status register flag.

Functional Description

A functional Block Diagram of the MT90826 is shown in Figure 1.

Data and Connection Memory

For all data rates, the received serial data is converted to parallel format by internal serial-to-parallel converters and stored sequentially in the data memory. Depending upon the selected operation programmed in the control register, the usable data memory may be as large as 4,096 bytes. The sequential addressing of the data memory is performed by an internal counter, which is reset by the input 8 kHz frame pulse $(\overline{\text{F0i}})$ to mark the frame boundaries of the incoming serial data streams.

Data to be output on the serial streams may come from either the data memory or connection memory.

Serial Interface Mode	Input Stream	Input Data Rate	Output Stream	Output Data Rate
8 Mb/s	STi0-31	8 Mb/s	STo0-31	8 Mb/s
16 Mb/s	STi0-15	16 Mb/s	STo0-15	16 Mb/s
4 Mb/s and 8 Mb/s	STi0-15	4 Mbs/	STo0-15	4 Mb/s
	STi15-31	8 Mb/s	STo16-31	8 Mb/s
16 Mb/s and 8 Mb/s	STi0-11	16 Mb/s	STo0-11	16 Mb/s
	STi12-19	8 Mb/s	STo12-19	8 Mb/s
4 Mb/s	STi0-31	4 Mb/s	STo0-31	4 Mb/s
2 Mb/s and 4 Mb/s	STi0-15	2 Mb/s	STo0-15	2 Mb/s
	STi16-31	4 Mb/s	STo16-31	4 Mb/s
2 Mb/s	STi0-31	2 Mb/s	STo0-31	2 Mb/s

Table 1 - Stream Usage and External Clock Rates

Locations in the connection memory are associated with particular ST-BUS output channels. When a channel is due to be transmitted on an ST-BUS output, the data for this channel can be switched either from an ST-BUS input in connection mode, or from the lower half of the connection memory in message mode. Data destined for a particular channel on a serial output stream is read from the data memory or connection memory during the previous channel timeslot. This allows enough time for memory access and parallel-to-serial conversion.

Connection and Message Modes

In the connection mode, the addresses of the input source data for all output channels are stored in the connection memory. The connection memory is mapped in such a way that each location corresponds to an output channel on the output streams. For details on the use of the source address data (CAB and SAB bits), see Table 18. Once the source address bits are programmed by the microprocessor, the contents of the data memory at the selected address are transferred to the parallel-to-serial converters and then onto an ST-BUS output stream.

By having several output channels connected to the same input source channel, data can be broadcasted from one input channel to several output channels.

In message mode, the microprocessor writes data to the connection memory locations corresponding to the output stream and channel number. The lower half (8 least significant bits) of the connection memory content is transferred directly to the parallelto-serial converter. This data will be output on the ST-BUS streams in every frame until the data is changed by the microprocessor.

The three most significant bits of the connection memory controls the following for an output channel: message or connection mode, constant or variable delay mode, enables/tristate the ST-BUS output

drivers and bit error test pattern enable. If an output channel is set to a high-impedance state by setting the OE bit to zero in the connection memory, the STBUS output will be in a high impedance state for the duration of that channel. In addition to the perchannel control, all channels on the ST-BUS outputs can be placed in a high impedance state by pulling the ODE input pin low and programming the output stand by (OSB) bit in the control register to low. This action overrides the individual per-channel programming by the connection memory bits. See Table 2 for detail.

The connection memory data can be accessed via the microprocessor interface through the D0 to D15 pins. The addressing of the device internal registers, data and connection memories is performed through the address input pins and the Memory Select (MS) bit of the control register.

Clock Timing Requirements

The master clock ($\overline{\text{CLK}}$) frequency must be either at 8.192 or 16.384MHz for serial data rate of 2.048, 4.096, 8.192 and 16.384Mb/s; see Table 6 for the selections of the master clock frequency.

Switching Configurations

The MT90826 maximum non-blocking switching configurations is determined by the data rates selected for the serial inputs and outputs. The switching configuration is selected by three DR bits in the control register. See Table 5 and Table 6.

8Mb/s mode (DR2=0, DR1=0, DR0=0)

When the 8Mb/s mode is selected, the device is configured with 32-input/32-output data streams each having 128 64Kbit/s channels. This mode allows a maximum non-blocking capacity of 4,096 x 4,096 channels. Table 1 summarizes the switching configurations and the relationship between different serial data rates and the master clock frequencies.

ODE pin	OSB bit in Control register	OE bit in Connection Memory	ST-BUS Output Driver
0	0	Х	High-Z
Х	X	0	Per Channel High-Z
1	0	1	Enable
0	1	1	Enable
1	1	1	Enable

Table 2 - Output High Impedance Control

16Mb/s mode (DR2=0, DR1=0, DR0 =1)

When the 16Mb/s mode is selected, the device is configured with 16-input/16-output data streams each having 256 64Kbit/s channels. This mode allows a maximum non-blocking capacity of 4,096 x 4,096 channels.

4Mb/s and 8Mb/s mode (DR2=0, DR1=1, DR0=0)

When the 4Mb/s and 8Mb/s mode is selected, the device is configured with 32-input/32-output data streams. STi0-15/STo0-15 have a data rate of 4Mb/s and STi16-31/STo16-31 have a data rate of 8Mb/s. This mode allows a maximum non-blocking capacity of 3,072 x 3,072 channels.

16Mb/s and 8Mb/s mode (DR2=0, DR1=1, DR0=1)

When the 16Mb/s and 8Mb/s mode is selected, the device is configured with 20-input/20-output data streams. STi0-11/STo0-11 have a data rate of 16Mb/s and STi12-19/STo12-19 have a data rate of 8Mb/s. This mode allows a maximum non-blocking capacity of 4,096 x 4,096 channels.

4Mb/s mode (DR2=1, DR1=0, DR0=0)

When the 4Mb/s mode is selected, the device is configured with 32-input/32-output data streams each having 64 64Kbit/s channels. This mode allows a maximum non-blocking capacity of 2,048 x 2,048 channels.

2Mb/s and 4Mb/s mode (DR2=1, DR1=0, DR0=1)

When the 2Mb/s and 4Mb/s mode is selected, the device is configured with 32-input/32-output data streams. STi0-15/STo0-15 have a data rate of 2Mb/s and STi16-31/STo16-31 have a data rate of 4Mb/s. This mode allows a maximum non-blocking capacity of 1,536 x 1,536 channels.

2Mb/s mode (DR2=1, DR1=1, DR0 =0)

When the 2Mb/s mode is selected, the device is configured with 32-input/32-output data streams each having 32 64Kbit/s channels. This mode allows a maximum non-blocking capacity of 1,024 x 1,024 channels.

Serial Input Frame Alignment Evaluation

The MT90826 provides the frame evaluation inputs, FEi0 to FEi31, to determine different data input delays with respect to the frame pulse $\overline{\text{F0i}}$. By using the frame evaluation input select bits (FE0 to FE4) of the frame alignment register (FAR), users can select one of the thirty-two frame evaluation inputs for the frame alignment measurement.

The internal master clock, which has a fixed relationship with the CLK and F0i depending upon the mode of operation, is used as the reference timing signal to determine the input frame delays. See Figure 4 for the signal alignments between the internal and the external master clocks.

A measurement cycle is started by setting the start frame evaluation (SFE) bit low for at least one frame. Then the evaluation starts when the SFE bit in the control register is changed from low to high. Two frames later, the complete frame evaluation (CFE) bit of the frame alignment register changes from low to high to signal that a valid offset measurement is ready to be read from bits 0 to 9 of the FAR register. The SFE bit must be set to zero before a new measurement cycle started.

The falling edge of the frame measurement signal (FEi) is evaluated against the falling edge of the frame pulse $(\overline{F0i})$. See Table 7 for the description of the frame alignment register.

Input Frame Offset Selection

Input frame offset selection allows the channel alignment of individual input streams, which operate at 4.096Mb/s, 8.192Mb/s or 16.384Mb/s, to be shifted against the input frame pulse (F0i). The input offset selection is not available for streams operated at 2.048Mb/s. This feature is useful in compensating for variable path delays caused by serial backplanes of variable lengths, which may be implemented in large centralized and distributed switching systems.

Each input stream has its own delay offset value programmed by the input delay offset registers. Each delay offset register can control 4 input streams. There are eight delay offset registers (DOS0 to DOS7) to control 32 input streams. Possible adjustment can range up to +4.5 internal master clock periods forward with resolution of 1/2 internal master clock period. See Table 8 and Table 9 for frame input delay offset programming.

Output Advance Offset Selection

The MT90826 allows users to advance individual output streams up to 45ns with a resolution of 15ns when the device is in 8Mb/s, 16Mb/s, 4 and 8 Mb/s or 16 and 8 Mb/s mode. The output delay adjustment is useful in compensating for variable output delays caused by various output loading conditions. The frame output offset registers (FOR0 & FOR3) control the output offset delays for each output streams via the programming of the OFn bits.

See Table 10 and Table 11 for the frame output offset programming.

Memory Block Programming

The MT90826 provides users with the capability of initializing the entire connection memory block in two frames. Bits 13 to 15 of every connection memory location will be programmed with the pattern stored in bits 13 to 15 of the control register.

The block programming mode is enabled by setting the memory block program (MBP) bit of the control register high. When the block programming enable (BPE) bit of the control register is set to high, the block programming data will be loaded into the bits 13 to 15 of every connection memory location. The other connection memory bits (bit 0 to 12) are loaded with zeros. When the memory block programming is complete, the device resets the BPE bit to zero.

Bit Error Monitoring

The MT90826 allows users to perform bit error monitoring by sending a pseudo random pattern to a selected ST-BUS output channel and receiving the pattern from a selected ST-BUS input channel. The pseudo random pattern is internally generated by the device with the polynomial of 2^{15} -1.

Users can select the pseudo random pattern to be presented on a ST-BUS channel by programming the TM0 and TM1 bits in the connection memory. When TM0 and TM1 bits are high, the pseudo random pattern is output to the selected ST-BUS output channel. The pseudo random pattern is then received by a ST-BUS input channel which is selected using the BSA and BCA bits in the bit error rate input register (BISR). An internal bit error counter keeps track of the error counts which is then stored in the bit error count register (BECR).

The bit error test is enabled and disabled by the SBER bit in the control register. Setting the bit from zero to one initiates the bit error test and enables the internal bit error counter. When the bit is programmed from one to zero, the internal bit error counter transfers the error counts to the bit error count register.

In the control register, a zero to one transition of the CBER bit resets the bit error count register and the internal bit error counter.

Delay Through the MT90826

The switching of information from the input serial streams to the output serial streams results in a throughput delay. The device can be programmed to perform timeslot interchange functions with different throughput delay capabilities on the per-channel basis. For voice application, select variable throughput delay to ensure minimum delay between input and output data. In wideband data applications, select constant throughput delay to maintain the frame integrity of the information through the switch.

The delay through the device varies according to the type of throughput delay selected by the TM bits in the connection memory.

Variable Delay Mode (TM1=0, TM0=0)

The delay in this mode is dependent only on the combination of source and destination channels and is independent of input and output streams.

Constant Delay Mode (TM1=1, TM0=0)

In this mode, frame integrity is maintained in all switching configurations by making use of a multiple data memory buffer.

Microprocessor Interface

The MT90826 provides a parallel microprocessor interface for non-multiplexed bus structures. This interface is compatible with Motorola non-multiplexed buses. The required microprocessor signals are the 16-bit data bus (D0-D15), 14-bit address bus (A0-A13) and 4 control lines (\overline{CS} , \overline{DS} , R/\overline{W} and \overline{DTA}). See Figure 14 for Motorola non-multiplexed microport timing.

The MT90826 microport provides access to the internal registers, connection and data memories. All locations provide read/write access except for the data memory, DRR and BECR registers which are read only.

For data memory read operations, two consecutive microprocessor cycles are required. The read address (A0-A13) should remain the same for the two consecutive read cycles. The data memory content from the first read cycle should be ignored. The correct data memory content will be presented to the data bus (D0-D15) on the second read cycle.

A13	A12	A11	A10	А9	A8	A 7	A6	A 5	A4	А3	A2	A 1	A0	Location
0	0	0	0	0	0	0	0	0	0	0	0	0	0	Control Register, CR
0	0	0	0	0	0	0	0	0	0	0	0	0	1	Frame Alignment Register, FAR
0	0	0	0	0	0	0	0	0	0	0	0	1	0	Input Offset Selection Register 0, DOS0
0	0	0	0	0	0	0	0	0	0	0	0	1	1	Input Offset Selection Register 1, DOS1
0	0	0	0	0	0	0	0	0	0	0	1	0	0	Input Offset Selection Register 2, DOS2
0	0	0	0	0	0	0	0	0	0	0	1	0	1	Input Offset Selection Register 3, DOS3
0	0	0	0	0	0	0	0	0	0	0	1	1	0	Input Offset Selection Register 4, DOS4
0	0	0	0	0	0	0	0	0	0	0	1	1	1	Input Offset Selection Register 5, DOS5
0	0	0	0	0	0	0	0	0	0	1	0	0	0	Input Offset Selection Register 6, DOS6
0	0	0	0	0	0	0	0	0	0	1	0	0	1	Input Offset Selection Register 7, DOS7
0	0	0	0	0	0	0	0	0	0	1	0	1	0	Frame Output Offset Register, FOR0
0	0	0	0	0	0	0	0	0	0	1	0	1	1	Frame Output Offset Register, FOR1
0	0	0	0	0	0	0	0	0	0	1	1	0	0	Frame Output Offset Register, FOR2
0	0	0	0	0	0	0	0	0	0	1	1	0	1	Frame Output Offset Register, FOR3
0	0	0	0	0	0	0	0	0	0	1	1	1	0	Unused
0	0	0	0	0	0	0	0	0	0	1	1	1	1	Unused
0	0	0	0	0	0	0	0	0	1	0	0	0	0	Unused
0	0	0	0	0	0	0	0	0	1	0	0	0	1	Bit Error Input Selection Register, BISR
0	0	0	0	0	0	0	0	0	1	0	0	1	0	Bit Error Count Register, BECR

Table 3 - Address Map for Registers (A13 = 0)

		s	tream A	Address	(ST0-31)				Cł	nannel	Addre	ess (Cl	n0-255	()
A13	A12	A11	A10	A9	A8	Stream Location	A7	A6	A5	A4	А3	A2	A 1	Α0	Channel Location
1	0	0	0	0	0	Stream 0	0	0	0	0	0	0	0	0	Ch 0
1	0	0	0	0	1	Stream 1	0	0	0	0	0	0	0	1	Ch 1
1	0	0	0	1	0	Stream 2	١.				١.	١.	١.		
1	0	0	0	1	1	Stream 3	١.				١.	١.	١.		
1	0	0	1	0	0	Stream 4	0	0	0	1	1	1	1	0	Ch 30
1	0	0	1	0	1	Stream 5	0	0	0	1	1	1	1	1	Ch 31 (Note 2)
1	0	0	1	1	0	Stream 6	0	0	1	0	0	0	0	0	Ch 32 ` ′
1	0	0	1	1	1	Stream 7	0	0	1	0	0	0	0	1	Ch 33
1	0	1	0	0	0	Stream 8						١.			
												١.			
							0	0	1	1	1	1	1	0	Ch 62
							0	0	1	1	1	1	1	1	Ch 63 (Note 3)
1	1	0	1	1	0	Stream 22	0	1	0	0	0	0	0	0	Ch 64
1	1	0	1	1	1	Stream 23	0	1	0	0	0	0	0	1	Ch 65
1	1	1	0	0	0	Stream 24									
1	1	1	0	0	1	Stream 25	0	1	1	1	1	1	1	0	Ch 126
1	1	1	0	1	0	Stream 26	0	1	1	1	1	1	1	1	Ch 127 (Note 4)
1	1	1	0	1	1	Stream 27	1	0	0	0	0	0	0	0	Ch 128
1	1	1	1	0	0	Stream 28	1	0	0	0	0	0	0	1	Ch 129
1	1	1	1	0	1	Stream 29						.			
1	1	1	1	1	0	Stream 30	1	1	1	1	1	1	1	0	Ch 254
1	1	1	1	1	1	Stream 31	1	1	1	1	1	1	1	1	Ch 255 (Note 5)

- 1. Bit A13 must be high for access to data and connection memory positions. Bit A13 must be low for access to registers.

 2. Channels 0 to 31 are used when serial stream is at 2Mb/s.

 3. Channels 0 to 63 are used when serial stream is at 4Mb/s

 4. Channels 0 to 127 are used when serial stream is at 8Mb/s

 5. Channels 0 to 255 are used when serial stream is at 16Mb/s

Table 4 - Address Map for Memory Locations (A13 = 1)

Memory Mapping

The address bus on the microprocessor interface selects the internal registers and memories of the MT90826. If the A13 address input is low, then the registers are addressed by A12 to A0 according to Table 3.

If the A13 is high, the remaining address input lines are used to select location in the data or connection memory depending upon MS bit in the control register. For data memory reads, the serial inputs are selected. For connection memory writes, the serial outputs are selected. The destination stream address bits and channel address bits are defined by A12 to A8 and A7 to A0 respectively. See Table 4 for the memory address mapping.

The control register controls all the major functions of the device. It selects the internal memory locations that specify the input and output channels selected for switching and should be programmed immediately after system power-up to establish the desired switching configuration as explained in the Frame Alignment Timing & Switching Configurations sections.

The data in the control register consists of the block programming bits (BPD0-2), the block programming enable bit (BPE), the memory block programming bit (MBP), the memory select bits (MS), the start frame evaluation bit (SFE), the output stand by bit (OSB), the wide frame pulse control bit (WFP) and the data rate selection bits (DR0-2). See Table 5 for the description of the control register bits.

Connection Memory Control

The connection memory controls the switching configuration of the device. Locations in the connection memory are associated with particular STo output streams.

The TM0 and TM1 bits of each connection memory location allows the selection of the variable throughput delay mode, the constant throughput delay mode, the message mode or the bit error test mode for all STo channels.

When the variable or constant throughput delay mode is selected, (TM1=0/1, TM0=0), the contents of the stream address bit (SAB) and the channel address bit (CAB) of the connection memory defines the source information (stream and channel) of the timeslot that will be switched to the STo streams.

When the message mode is selected, (TM1=0, TM0=1), only the lower half byte (8 least significant bits) of the connection memory is transferred to the associated STo output channel.

When the bit error test mode is selected, (TM1=1, TM0=1), the pseudo random pattern will be output on the associated STo output channel.

See Table 17 for the description of the connection memory bits.

DTA Data Transfer Acknowledgment Pin

The DTA pin is driven LOW by internal logic, to indicate to the CPU that a data bus transfer is complete. When the read or write cycle ends, this pin changes to the high-impedance state.

Initialization of the MT90826

During power up, the \overline{TRST} pin should be pulsed low, or held low continuously, to ensure that the MT90826 is in the normal functional mode. A 5K pull-down resistor can be connected to the \overline{TRST} pin so that the device will not enter the JTAG test mode during power up.

After power up, the contents of the connection memory can be in any state. The ODE pin should be held low after power up to keep all serial outputs in a high impedance state until the microprocessor has initialized the switching matrix. This procedure prevents two serial outputs from driving the same stream simultaneously.

During the microprocessor initialization routine, the microprocessor should program the desired active paths through the switch. Users can also consider using the memory block programming feature to quickly initialize the OE, TMO and TM1 bits in the connection memory. When this process is complete, the microprocessor controlling the matrices can either bring the ODE pin high or enable the OSB bit in control register to relinquish the high impedance state control.

Read/Write Address: 0000_H, 0000_H. Reset Value: 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0 BPD2 BPD1 BPD0 CPLL CBER SBER DR2 DR1 DR0 SFE 0 BPE MBP MS OSB

Bit	Name	Description								
15-13	BPD2-0	Block Programming Data. These bits carry the value to be loaded into the connection memory block whenever the memory block programming feature is activated. After the MBP bit is set to 1 and the BPE bit is set to 1, the contents of the bits BPD2- 0 are loaded into bit 15 to bit 13 of the connection memory. Bit 12 to bit 0 of the connection memory are set to 0.								
12	Unused	Must be zero for normal operation.								
11	CPLL	PLL Input Frequency Select. When zero, the CLK input is 16.384MHz. When 1, the CLK input is 8.192MHz or 16.384MHz. See Table 6 for the usage of the clock frequency.								
10	CBER	Clear Bit Error Rate Register. A zero to one transition in this bit resets the internal bit error counter and the bit error count register to zero.								
9	SBER	Start Bit Error Rate Test. A zero to one transition in this bit starts the bit error rate test. The bit error test result is kept in the bit error count register. A one to zero transition stops the bit error rate test and the internal bit error counter.								
8	SFE	Start Frame Evaluation. A zero to one transition in this bit starts the frame evaluation procedure. When the CFE bit in the frame alignement (FAR) register changes from zero to one, the evaluation procedure stops. To start another frame evaluation cycle, set this bit to zero.								
7	Unused	Must be zero for normal operation.								
6	BPE	Begin Block programming Enable. A zero to one transition of this bit enables the memory block programming function. The BPE and BPD2-0 bits have to be defined in the same write operation. Once the BPE bit is set high, the device requires two frames to complete the block programming. After the programming function has finished, the BPE bit returns to zero to indicate the operation is completed. When the BPE = 1, the BPE or MBP can be set to 0 to abort the programming operation. When BPE = 1, the other bits in the control register must not be changed for two frames to ensure proper operation.								
5	MBP	Memory Block Program. When 1, the connection memory block programming feature is ready to program Bit13 to Bit15 of the connection memory. When 0, feature is disabled.								
4	MS	Memory Select. When 0, connection memory is selected for read or write operations. When 1, the data memory is selected for read operations and connection memory is selected for write operations. (No microprocessor write operation is allowed for the data memory.)								
		For data memory read operations, two consecutive microprocessor cycles are required. The read address should remain the same for the two consecutive read cycles. The data memory content from the first read cycle should be ignored. The correct data memory content will be presented to the data bus on the second read cycle.								
3	OSB	Output Stand By. This bit controls the device output drivers. OSB bit ODE pin OE bit ST00 - 31 0 1 1 Enable 1 0 1 Enable 1 1 1 Enable 0 0 X High impedance state X X 0 Per-channel high impedance								
2 - 0	DR2-0	Data Rate Select. Input/Output data rate selection. See next table (Table 6) for detailed programming.								

Table 5 - Control Register Bits

DR2	DR1	DR0	Serial Interface Mode	CLK (CPLL=0)	CLK (CPLL=1)	
0	0	0	8 Mb/s			
0	0	1	16 Mb/s			
0	1	0	4 and 8 Mb/s	16.384MHz	16.384MHz	
0	1	1	16 and 8 Mb/s			
1	0	0	4 Mb/s	16.384MHz	8.192MHz	
1	0	1	2 and 4 Mb/s			
1	1	0	2 Mb/s	16.384MHz	8.192MHz	

Table 6 - Serial Data Rate Selections and External Clock Rates

	ad/Write Addeset Value:	dress:	0001 _H , 0000 _H .										
15	14 13	12	11 10	9	8	7	6	5	4	3	2	1	0
FE4	FE3 FE2	FE1	FE0 CFE	FD9	FD8	FD7	FD6	FD5	FD4	FD3	FD2	FD1	FD0
Bit	Name	Description											
15-11	FE4-	0		Frame Evaluation Input Select. The binary value expressed in these bits refers to the frame evaluation inputs, FEi0 to FEi31.									
10	CFE		Complete Frame Evaluation. When CFE = 1, the frame evaluation is completed and FD9 to FD0 bits contains a valid frame alignment offset. This bit is reset to zero, when SFE bit in the control register is changed from 1 to 0.							set.			
9	FD9		Frame Delay Bit 9. The falling edge of FEi input is sampled during the interpretation master clock high phase (FD9 = 1) or during the low phase (FD9 = 0). The allows the measurement resolution to 1/2 internal master clock cycle. See Figure 4 for clock signal alignment. Internal Master Clock C8i C9meration Mode C8i 2Mb/s C16i 4Mb/s, 2&4Mb/s C32i 8Mb/s, 16Mb/s, 4&8Mb/s, 16&8Mb/s)). This bit				
8-0	FD8-0)	Frame Delay Bits. The binary value expressed in these bits refers to the measured input offset value. These bits are reset to zero when the SFE bit of the control register changes from 1 to 0. (FD8 = MSB, FD0 = LSB)										

Table 7 - Frame Alignment (FAR) Register Bits

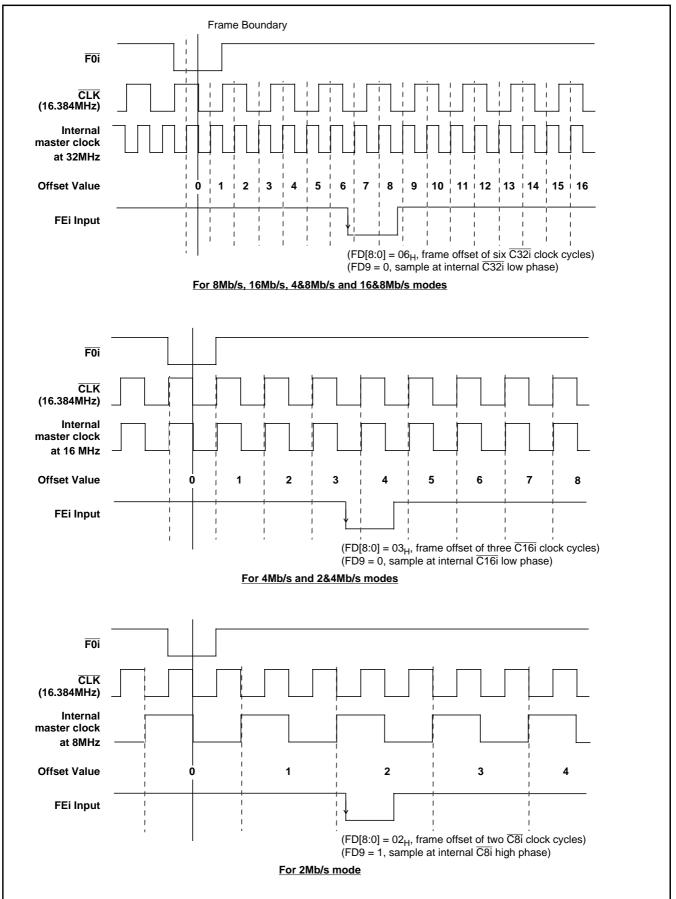


Figure 4 - Example for Frame Alignment Measurement

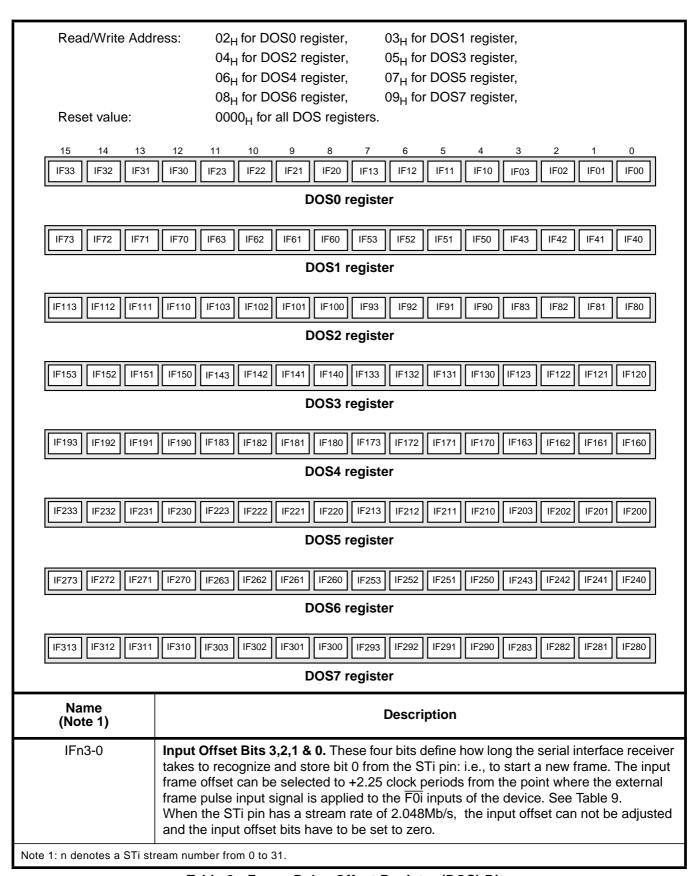


Table 8 - Frame Delay Offset Register (DOS) Bits

Input Stream Offset		urement rame De			Corresponding Input Offset Bits				
Onset	FD9	FD2	FD1	FD0	IFn3	IFn2	IFn1	IFn0	
No internal master clock shift (Default)	1	0	0	0	0	0	0	0	
+ 1/4 internal master clock shift	0	0	0	0	0	0	0	1	
+ 1/2 internal master clock shift	1	0	0	1	0	0	1	0	
+ 3/4 internal master clock shift	0	0	0	1	0	0	1	1	
+ 1.00 internal master clock shift	1	0	1	0	0	1	0	0	
+ 1.25 internal master clock shift	0	0	1	0	0	1	0	1	
+ 1.50 internal master clock shift	1	0	1	1	0	1	1	0	
+ 1.75 internal master clock shift	0	0	1	1	0	1	1	1	
+ 2.00 internal master clock shift	1	1	0	0	1	0	0	0	
+ 2.25 internal master clock shift	0	1	0	0	1	0	0	1	

Table 9 - Frame delay Bits (FD9, FD2-0) and Input Offset Bits (IFn3-0)

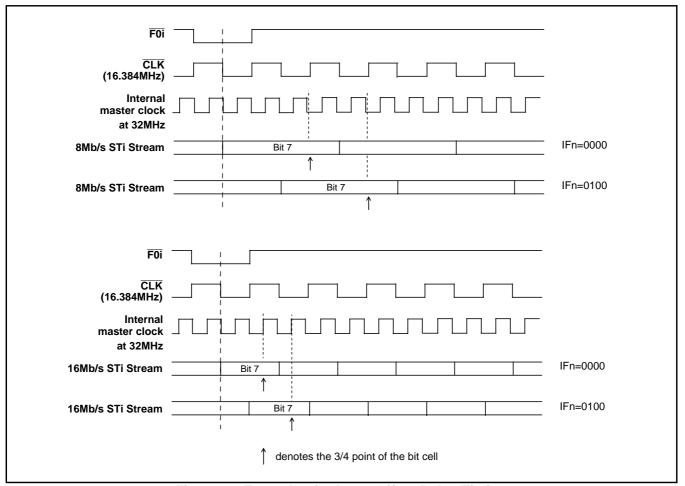


Figure 4 - Examples for Input Offset Delay Timing

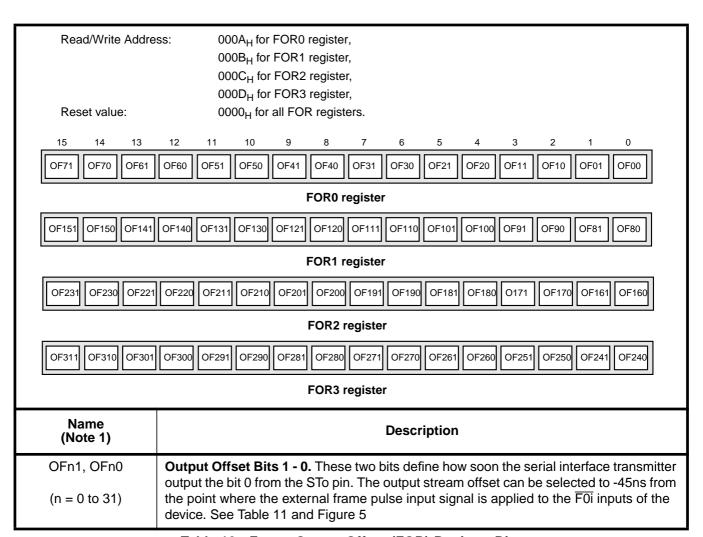


Table 10 - Frame Output Offset (FOR) Register Bits

Corresponding O	utput Offset Bits	Output Stream Offset for 8Mb/s, 16Mb/s, 4&8Mb/s and 16&8Mb/s modes
OFn1	OFn0	(Not available for 2Mb/s, 4Mb/s and 2&4 Mb/s modes)
0	0	0ns
0	1	-15ns
1	0	-30ns
1	1	-45ns

Table 11 - Output Offset Bits (FD9, FD2-0)

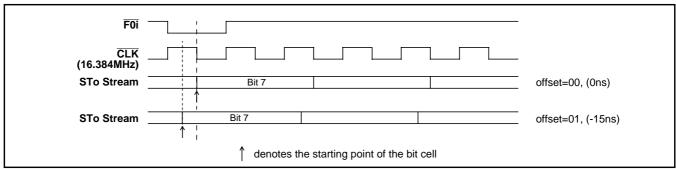


Figure 5 - Examples for Frame Output Offset Timing

Read/Write Address: 0011_H for BISR register, Reset value: 0000_{H} 7 6 2 15 14 13 12 11 10 8 3 0 BSA3 BCA2 BCA1 BSA4 BSA2 BSA1 BSA0 BCA7 BCA6 BCA5 BCA4 BCA3 BCA0 0 Bit Name **Description** 12 - 8 BSA4 - BSA0 BER Input Stream Address Bits. The number expressed in binary notation on these bits refers to the input data stream which receives the pseudo random pattern. 7 - 0 BCA7 - BCA0 BER Input Channel Address Bits. The number expressed in binary notation on these bits refers to the input channel which receives the pseudo random pattern.

Table 12 - Bit Error Input Selection (BISR) Register Bits

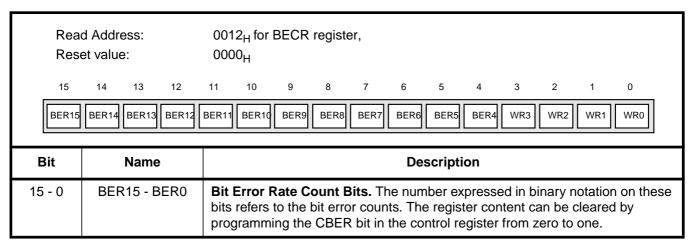


Table 13 - Bit Error Count (BECR) Register Bits

Table 14 - Connection Memory Bits

Data Rate	SAB4 to SAB0 Bits Used to Determine the Source Stream of the connection	CAB Bits Used to Determine the Source Channel of the Connection
8 Mb/s	SAB4 to SAB0 (STi0 to STi31)	CAB6 to CAB0 (128 channel/frame)
16Mb/s	SAB3 to SAB0 (STi0 to STi15)	CAB7 to CAB0 (256 channel/frame)
4 Mb/s & 8 Mb/s	SAB4 to SAB0 (STi0 to STi31)	CAB6 to CAB0 (64 or 128 channel/frame)
16 Mb/s & 8 Mb/s	SAB3 to SAB0 (STi0 to STi19)	CAB7 to CAB0 (128 or 256 channel/frame)
4 Mb/s	SAB4 to SAB0 (STi0 to STi31)	CAB5 to CAB0 (64 channel/frame)
2 Mb/s & 4 Mb/s	SAB4 to SAB0 (STi0 to STi31)	CAB5 to CAB0 (32 or 64 channel/frame)
2 Mb/s	SAB4 to SAB0 (STi0 to STi31)	CAB4 to CAB0 (32 channel/frame)

Table 15 - SAB and CAB Bits Programming for various interface mode

JTAG Support

The MT90826 JTAG interface conforms to the Boundary-Scan standard IEEE1149.1. This standard specifies a design-for-testability technique called Boundary-Scan test (BST). The operation of the boundary-scan circuitry is controlled by an external test access port (TAP) Controller.

Test Access Port (TAP)

The Test Access Port (TAP) provides access to the many test functions of the MT90826. It consists of three input pins and one output pin. The following pins are from the TAP.

- Test Clock Input (TCK)
 TCK provides the clock for the test logic. The
 TCK does not interfere with any on-chip clock
 and thus remain independent. The TCK permits
 shifting of test data into or out of the Boundary Scan register cells concurrently with the
 operation of the device and without interfering
 with the on-chip logic.
- Test Mode Select Input (TMS)
 The logic signals received at the TMS input are interpreted by the TAP Controller to control the test operations. The TMS signals are sampled at the rising edge of the TCK pulse. This pin is internally pulled to Vdd when it is not driven from an external source.
- Test Data Input (TDI)
 Serial input data applied to this port is fed either into the instruction register or into a test data register, depending on the sequence previously applied to the TMS input. Both registers are described in a subsequent section. The received input data is sampled at the rising edge of TCK pulses. This pin is internally pulled to Vdd when it is not driven from an external source.
- Test Data Output (TDO)
 Depending on the sequence previously applied to the TMS input, the contents of either the instruction register or data register are serially shifted out towards the TDO. The data out of the TDO is clocked on the falling edge of the TCK pulses. When no data is shifted through the boundary scan cells, the TDO driver is set to a high impedance state.

Test Reset (TRST)
Resets the JTAG scan structure. This pin is internally pulled to VDD.

Instruction Register

In accordance with the IEEE 1149.1 standard, the MT90863 uses public instructions. The JTAG Interface contains a two-bit instruction register. Instructions are serially loaded into the instruction register from the TDI when the TAP Controller is in its shifted-IR state. Subsequently, the instructions are decoded to achieve two basic functions: to select the test data register that may operate while the instruction is current, and to define the serial test data register path, which is used to shift data between TDI and DO during data register scanning.

Test Data Register

As specified in IEEE 1149.1, the MT90826 JTAG Interface contains three test data registers:

- The Boundary-Scan register
 The Boundary-Scan register consists of a series of Boundary-Scan cells arranged to form a scan path around the boundary of the MT90863 core logic.
- The Bypass Register
 The Bypass register is a single stage shift register that provides a one-bit path from TDI to its TDO.
- The Device Identification Register
 The device identification register is a 32-bit register with the register contain of:

MSB LSB 0000 0000 1000 0010 0110 0001 0100 1011

The LSB bit in the device identification register is the first bit clock out.

The MT90826 scan register contains 165 bits.

	Bounda	ry Scan Bit 0 t	to Bit 165
Device Pin	Tri-state Control	Output Scan Cell	Input Scan Cell
F0i CLK ODE			0 1 2
STi0 STi1 STi2 STi3 STo0 STo1 STo2 STo3	7 9 11 13	8 10 12 14	3 4 5 6
STi4 STi5 STi6 STi7 STo4 STo5 STo6 STo7	19 21 23 25	20 22 24 26	15 16 17 18
STi8	31 33 35 37	32 34 36 38	27 28 29 30
STi13 STi14 STi15 STo12 STo13 STo14 STo15 STi16	43 45 47 49	44 46 48 50	40 41 42 51
STi17 STi18 STi19 STo16 STo17 STo18 STo19 STi20	55 57 69 61	56 58 60 62	52 53 54 63
STi21 STi22 STi23 STo20 STo21 STo22 STo23	67 69 71 73	68 70 72 74	64 65 66
STi24 STi25 STi26 STi27 STo24 STo25 STo26 STo27	79 81 83 85	80 82 84 86	75 76 77 78

	Bounda	ry Scan Bit 0 t	to Bit 165
Device Pin	Tri-state Control	Output Scan Cell	Input Scan Cell
STi28 STi29 STi30 STi31 STo28 ST029 ST030 STo31	91 93 95 97	92 94 96 98	87 88 89 90
D0 D1 D2 D3 D4 D5 D6 D7 D8 D9 D10 D11 D12 D13 D14 D15	99 102 105 108 111 114 117 120 123 126 129 132 135 138 141 144	100 103 106 109 112 115 118 121 124 127 130 133 136 139 142	101 104 107 110 113 116 119 122 125 128 131 134 137 140 143
DTA CS R/W DS		147	148 149 150
A0 A1 A2 A3 A4 A5 A6 A7 A8 A9 A10 A11 A12 A13 RESETb			151 152 153 154 155 156 157 158 159 160 161 162 163 164 165

CMOS

Absolute Maximum Ratings*

	Parameter	Symbol	Min	Max	Units
1	Supply Voltage	V_{DD}	-0.3	5.0	V
2	Voltage on any 3.3V tolerant pin I/O (other than supply pins)	V _I	V _{SS} - 0.3	V _{DD} + 0.3	V
3	Voltage on any 5V tolerant pin I/O (other than supply pins)	VI	V _{SS} - 0.3	5.0	V
4	Continuous Current at digital outputs	Io		20	mA
5	Package power dissipation	P _D		1	W
6	Storage temperature	T _S	- 65	+125	°C

^{*} Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied

$\textbf{Recommended Operating Conditions -} \ \ \textit{Voltages are with respect to ground (V}_{\textit{SS}} \textit{) unless otherwise stated.}$

	Characteristics	Sym	Min	Тур	Max	Units	Test Conditions
1	Operating Temperature	T _{OP}	-40		+85	°C	
2	Positive Supply	V_{DD}	3.0		3.6	V	
3	Input High Voltage	V _{IH}	0.7V _{DD}		V _{DD}	V	
4	Input High Voltage on 5V Tolerant Inputs	V _{IH}			5.5	V	
5	Input Low Voltage	V _{IL}	V _{SS}		0.3V _{DD}	V	

DC Electrical Characteristics - Voltages are with respect to ground (Vss) unless otherwise stated.

		Characteristics	Sym	Min	Тур	Max	Units	Test Conditions
1		Supply Current	I _{DD}		64	100	mA	Output unloaded
2		Input High Voltage	V _{IH}	0.7V _{DD}			V	
3	N	Input Low Voltage	V _{IL}			0.3V _{DD}	V	
4	U T S	Input Leakage (input pins) Input Leakage (with pull-up or pull-down)	I _{IL} I _{BL}			15 50	μA μA	0≤ <v≤v<sub>DD See Note 1</v≤v<sub>
5		Input Pin Capacitance	C _I			10	pF	
6	0	Output High Voltage	V _{OH}	0.8V _{DD}			V	I _{OH} = 10mA
7	T	Output Low Voltage	V _{OL}			0.4	V	I _{OL} = 10mA
8	Ü	High Impedance Leakage	I _{OZ}			5	μΑ	0 < V < V _{DD} See Note 1
9	S	Output Pin Capacitance	Co			10	pF	

Note:

AC Electrical Characteristics - Timing Parameter Measurement Voltage Levels

	Characteristics	Sym	Level	Units	Conditions
1	CMOS Threshold Voltage	V _{TT}	0.5V _{DD}	V	
2	CMOS Rise/Fall Threshold Voltage High	V _{HM}	0.7V _{DD}	V	
3	CMOS Rise/Fall Threshold Voltage Low	V _{LM}	0.3V _{DD}	V	

^{1.} Maximum leakage on pins (output or I/O pins in high impedance state) is over an applied voltage (V)

AC Electrical Characteristics - Frame Pulse and CLK

	Characteristic	Sym	Min	Тур	Max	Units	CLK
1	Frame pulse width	t _{FPW}	55		65	ns	
2	Frame Pulse Setup time before CLK falling	t _{FPS}	5			ns	16.384MHz
3	Frame Pulse Hold Time from CLK falling	t _{FPH}	10			ns	
4	CLK Period	t _{CP}	55		70	ns	
5	CLK Pulse Width High	t _{CH}	20		40	ns	
6	CLK Pulse Width Low	t _{CL}	20		40	ns	
7	Frame pulse width	t _{FPW8}	115		145	ns	8.192MHz
8	Frame Pulse Setup time before CLK falling	t _{FPS8}	5			ns	
9	Frame Pulse Hold Time from CLK falling	t _{FPH8}	10			ns	
10	CLK Period	t _{CP8}	110		150	ns	
11	CLK Pulse Width High	t _{CH8}	50		75	ns	
12	CLK Pulse Width Low	t _{CL8}	50		75	ns	
13	Clock Rise/Fall Time	t _r , t _f	-10		+10	ns	

AC Electrical Characteristics - Serial Streams for ST-BUS

	Characteristic	Sym	Min	Тур	Max	Units	Test Conditions
1	STi Set-up Time	t _{SIS}	0			ns	
2	STi Hold Time	t _{SIH}	8			ns	
3	STo Delay - Active to Active	t _{SOD}	8 11		30 43	ns	C _L =30pF C _L =200pF
4	Output Driver Enable (ODE) Delay	t _{ODE}			35	ns	R _L =1K, C _L =200pF, See Note 1
5	STo delay - Active to High-Z - High-Z to Active	t _{ZD}			35	ns	R _L =1K, C _L =200pF, See Note 1

Note:1. High Impedance is measured by pulling to the appropriate rail with R_L, with timing corrected to cancel time taken to discharge C_L.

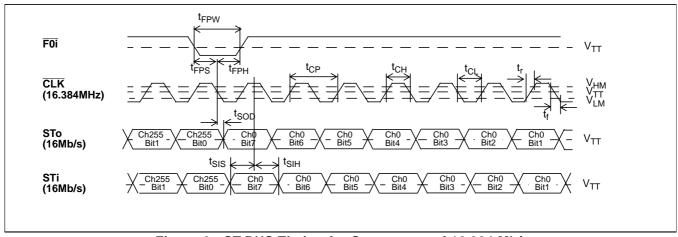


Figure 6 - ST-BUS Timing for Stream rate of 16.384 Mb/s

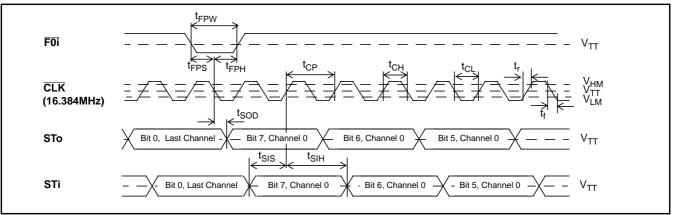


Figure 7 - ST-BUS Timing for Stream rate of 8.192 Mb/s

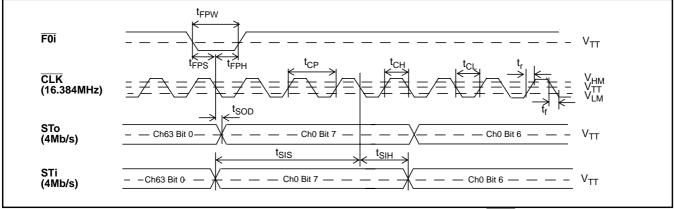


Figure 8 - ST-BUS Timing for Stream rate of 4.096 Mb/s when CLK = 16.384MHz

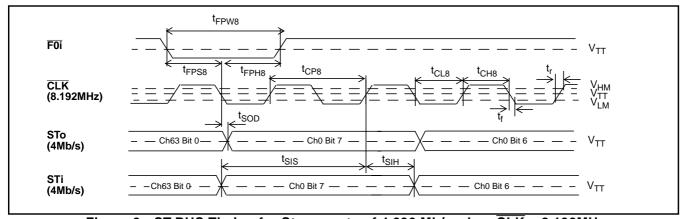


Figure 9 - ST-BUS Timing for Stream rate of 4.096 Mb/s when CLK = 8.192MHz

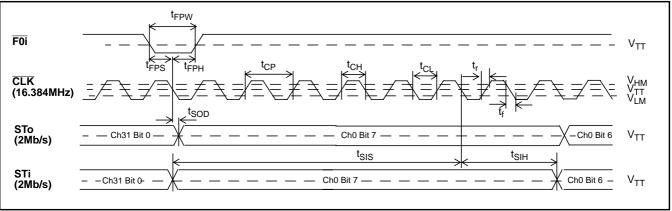


Figure 10 - ST-BUS Timing for Stream rate of 2.048 Mb/s when CLK = 16.384MHz

Figure 11 - ST-BUS Timing for Stream rate of 2.048 Mb/s when CLK = 8.192MHzMHz

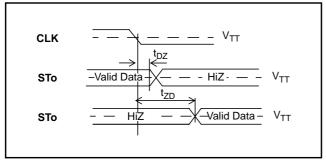


Figure 12 - Serial Output and External Control

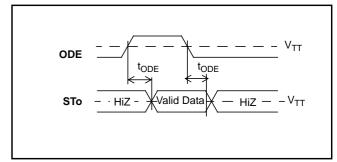


Figure 13 - Output Driver Enable (ODE)

AC Electrical Characteristics - Motorola Non-Multiplexed Bus Mode

	Characteristics	Sym	Min	Тур	Max	Units	Test Conditions
1	CS setup from DS falling	t _{CSS}	0			ns	
2	R/W setup from DS falling	t _{RWS}	10			ns	
3	Address setup from DS falling	t _{ADS}	2			ns	
4	CS hold after DS rising	t _{CSH}	0			ns	
5	R/W hold after DS rising	t _{RWH}	2			ns	
6	Address hold after DS rising	t _{ADH}	10			ns	
7	Data setup from DTA Low on Read	t _{DDR}	27			ns	C _L =150pF
8	Data hold on read	t _{DHR}	12		20	ns	C _L =150pF, R _L =1K Note 1
9	Data setup on write (fast write)	t _{DSW}	0			ns	
10	Valid Data Delay on write (slow write)	t _{SWD}	50 85 185			ns	
11	Data hold on write	t _{DHW}	13			ns	
12a	Acknowledgment Delay: Register RD or WR	t _{AKD}			55	ns	C _L =150pF
12b	Acknowledgment Delay: Memory RD or WR 16Mb/s, 16&8Mb/s, 8Mb/s, 4&8Mb/s 4Mb/s, 4&2Mb/s 2Mb/s	t _{AKD}			100 140 240	ns ns ns	C _L =150pF
13	Acknowledgment Hold Time	t _{AKH}			24	ns	C _L =150pF, R _L =1K, Note 1

Note:

^{1.} High Impedance is measured by pulling to the appropriate rail with R_L, with timing corrected to cancel time taken to discharge C_L.

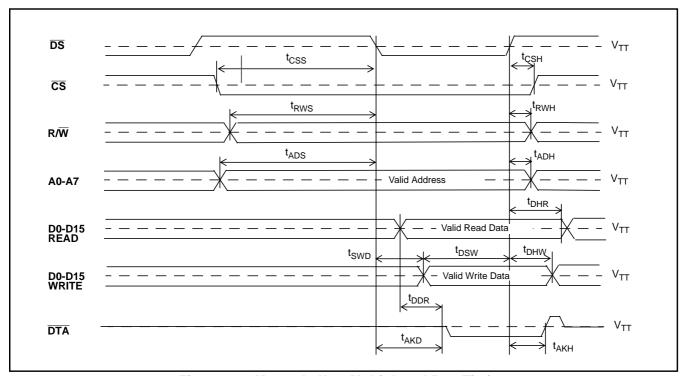
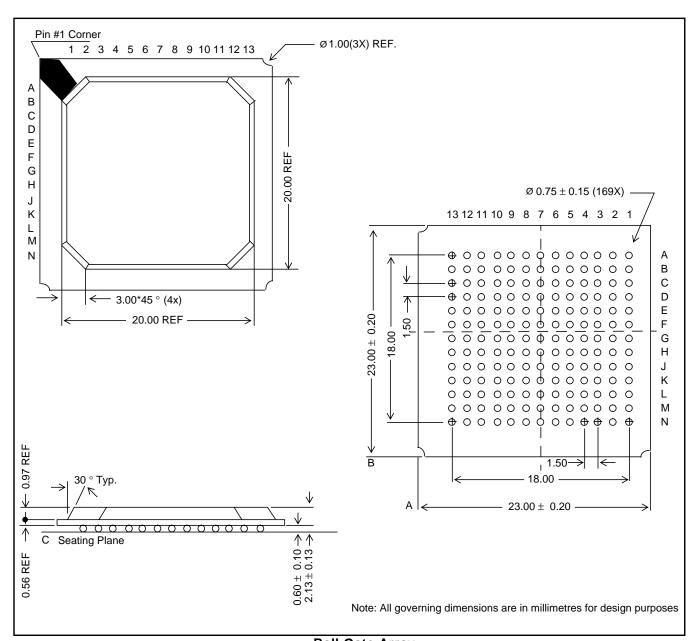
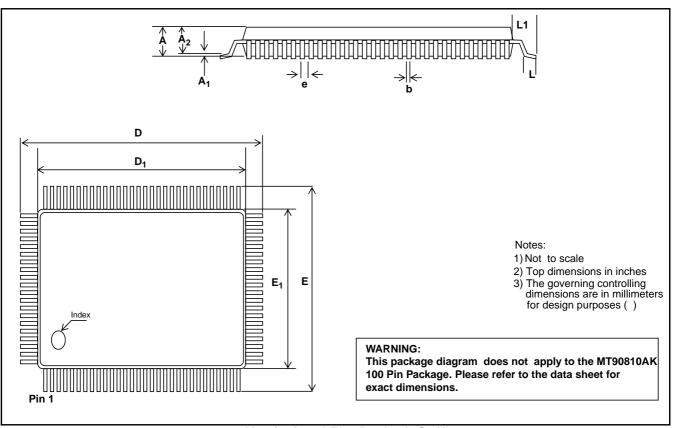


Figure 14 - Motorola Non-Multiplexed Bus Timing



Ball Gate Array

120-BGA	144-BGA	160-BGA
MT90823	MT90863	MT90826



Metric Quad Flat Pack - L Suffix

Dim	44-	Pin	64-	Pin	100-	-Pin	128	-Pin
ווווט	Min	Max	Min	Max	Min	Max	Min	Max
Α	-	0.096 (2.45)	-	0.134 (3.40)	-	0.134 (3.40)	-	0.154 (3.85)
A1	0.01 (0.25)	-	0.01 (0.25)	-	0.01 (0.25)	-	0.00	0.01 (0.25)
A2	0.077 (1.95)	0.083 (2.10)	0.1 (2.55)	0.12 (3.05)	0.1 (2.55)	0.12 (3.05)	0.125 (3.17)	0.144 (3.60)
b	0.01 (0.30)	0.018 (0.45)	0.013 (0.35)	0.02 (0.50)	0.009 (0.22)	0.015 (0.38)	0.019 (0.30)	0.018 (0.45)
D	0.547 (13.90		0.941 (23.90	BSC BSC)	0.941 BSC (23.90 BSC)		1.23 BSC (31.2 BSC)	
D ₁	0.394 (10.00		0.787 (20.00	BSC BSC)	0.787 BSC (20.00 BSC)		1.102 BSC (28.00 BSC)	
E	0.547 (13.90		0.705 (17.90	BSC BSC)	0.705 (17.90		1.23 BSC (31.2 BSC)	
E ₁	0.394 (10.00		0.551 (14.00		0.551 (14.00		1.102 (28.00	
е	0.031 (0.80	BSC BSC)	0.039 (1.0 l		0.256 BSC (0.65 BSC)		0.031 (0.80	
L	0.029 (0.73)	0.04 (1.03)	0.029 (0.73)	0.04 (1.03)	0.029 0.04 (0.73) (1.03)		0.029 (0.73)	0.04 (1.03)
L1	0.077 (1.95		0.077 REF (1.95 REF)		0.077 REF (1.95 REF)		0.063 (1.60	

NOTE: Governing controlling dimensions in parenthesis () are in millimeters.

Package Outlines

Dim	160-Pin		208-Pin		240-Pin	
	Min	Max	Min	Max	Min	Max
Α	-	0.154 (3.92)		.161 (4.10)	-	0.161 (4.10)
A1		0.01 (0.25)	0.01 (0.25)	0.02 (0.50)	0.01 (0.25)	0.02 (0.50)
A2	0.125	0.144	.126	.142	0.126	0.142
	(3.17)	(3.67)	(3.20)	(3.60)	(3.2)	(3.60)
b	0.009	0.015	.007	.011	0.007	0.010
	(0.22)	(0.38)	(0.17)	(0.27)	(0.17)	(0.27)
D	1.23 BSC		1.204		1.360 BSC	
	(31.2 BSC)		(30.6)		(34.6 BSC)	
D ₁	1.102 BSC		1.102		1.26 BSC	
	(28.00 BSC)		(28.00)		(32.00 BSC)	
E	1.23 BSC		1.204 BSC		1.360 BSC	
	(31.2 BSC)		(30.6 BSC)		(34.6 BSC)	
E ₁	1.102 BSC		1.102 BSC		1.26 BSC	
	(28.00 BSC)		(28.00 BSC)		(32.00 BSC)	
е	0.025 BSC		0.020 BSC		0.0197 BSC	
	(0.65 BSC)		(0.50 BSC)		(0.50 BSC)	
L	0.029	0.04	0.018	0.029	0.018	0.029
	(0.73)	(1.03)	(0.45)	(0.75)	(0.45)	(0.75)
L1	0.063 REF		0.051 REF		0.051 REF	
	(1.60 REF)		(1.30 REF)		(1.30 REF)	

NOTE: Governing controlling dimensions in parenthesis () are in millimeters.



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